

**Bump Site Transfer and Qualification of Select 6L and 8L SOT23
Flip Chip on Lead Packages**

**Qualification Plan Summary for
SOT at CARSEM**

TEST	SPECIFICATION	SAMPLE SIZE	EXPECTED COMPLETION DATE
Temperature Cycle (TC)*	JEDEC <i>JESD22-A104</i>	3 x 77	Sept 2018
Solder Heat Resistance (SHR)*	JEDEC/IPC <i>J-STD-020</i>	3 x 11	Sept 2018
Temperature, Humidity and Bias Test (THB)*	JEDEC <i>JESD22-A101</i>	3 x 77	Sept 2018
High Temperature Storage (HTS)	JEDEC <i>JESD22-A103</i>	1 x 77	Sept 2018
Electrostatic Discharge <i>Field Induced Charge Device Model</i>	ANSI/ESDA/JEDEC <i>JS-002-2014</i>	3/voltage	Sept 2018

* Preconditioned per JEDEEC/IPC J-STD0020.